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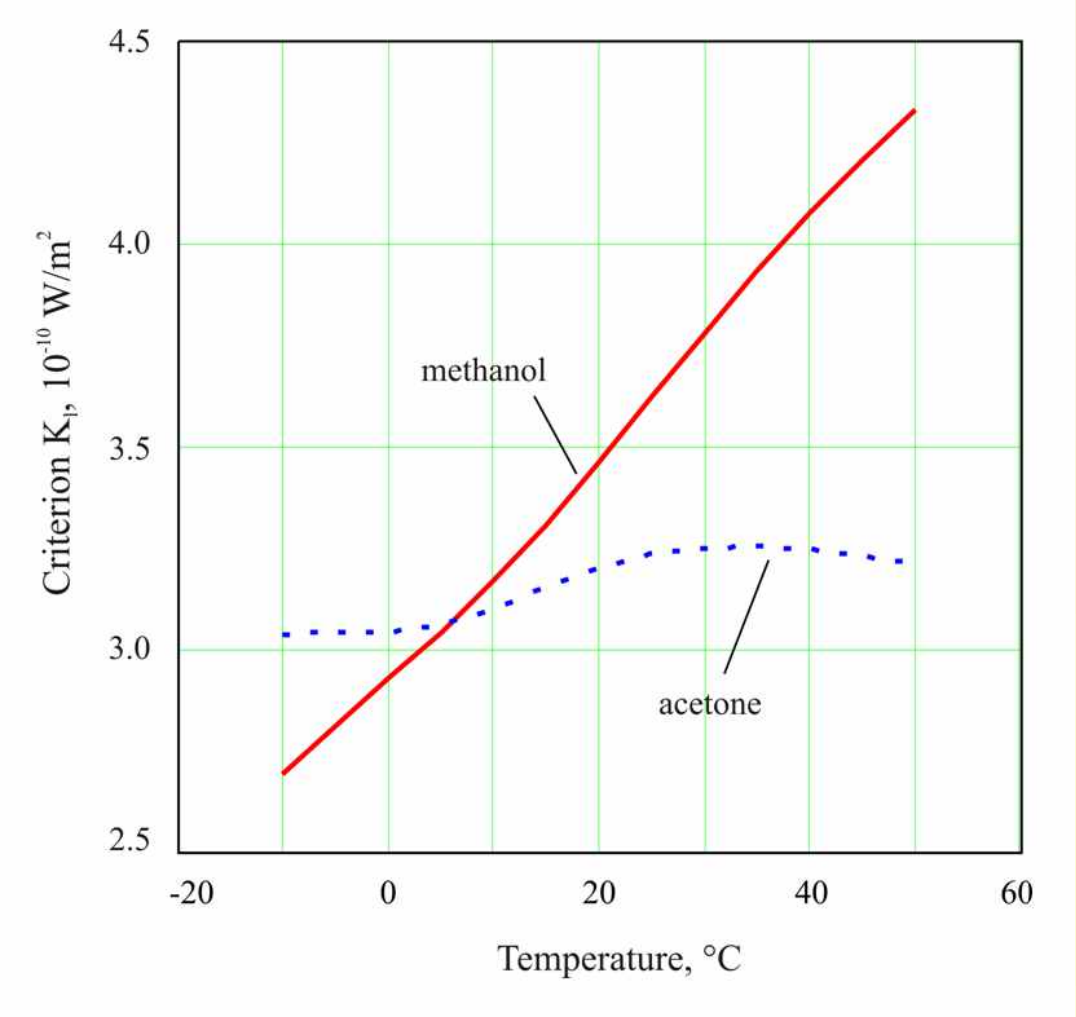


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The figure on the front cover is from the article published in Journal of Electronics Cooling and Thermal Control, 2015, Vol. 5, No. 4, pp. 77-88 by Yury F. Maydanik, Vladimir G. Pastukhov and Mariya A. Chernysheva.

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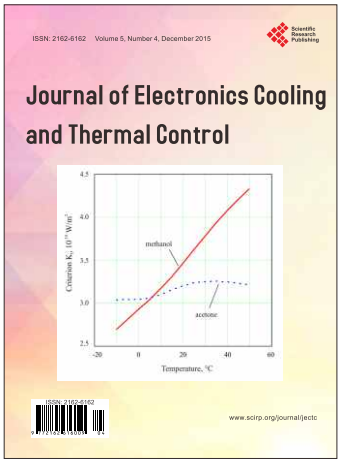


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# Journal of Electronics Cooling and Thermal Control

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